L	Hits	Search Text	DB	Time stamp
Number				
1	1	5895223.pn.	USPAT;	2002/12/13
	1		EPO; JPO;	12:36
			IBM TDB	
2	1185		USPAT;	2002/12/13
		etch\$5 and (Pt or platinum or Au or gold	EPO; JPO;	12:50
		or Pd or palladium)	IBM TDB	
3	753	(porous and (HF or Hydrofluoric) and	USPAT;	2002/12/13
		etch\$5 and (Pt or platinum or Au or gold	EPO; JPO;	12:43
		or Pd or palladium)) and semiconductor	IBM TDB	
5	600		USPAT;	2002/12/13
		etch\$5 and (Pt or platinum or Au or gold	EPO; JPO;	13:34
		or Pd or palladium)) and semiconductor)	IBM TDB	
		and electrodes		
7	1829	electrochemical near4 etch\$5	USPAT;	2002/12/13
	1023	010011001101112011111111111111111111111	EPO; JPO;	12:50
			IBM TDB	
8	111	(electrochemical near4 etch\$5) and	USPAT;	2002/12/13
	111	(porous and (HF or Hydrofluoric) and	EPO; JPO;	12:50
		etch\$5 and (Pt or platinum or Au or gold	IBM TDB	
		or Pd or palladium))	12132	
9	84	stain near etch\$5	USPAT;	2002/12/13
	"	Starii ilear ettiiv	EPO; JPO;	13:35
	1		IBM TDB	13.33
16	131887	"porous silicon" or PSi	USPAT;	2002/12/13
	131007	polous silicon of rsi	EPO; JPO;	13:44
			IBM TDB	13.11
17	403	("porous silicon" or PSi) and (porous and	USPAT;	2002/12/13
17	103	(HF or Hydrofluoric) and etch\$5 and (Pt	EPO; JPO;	13:44
		or platinum or Au or gold or Pd or	IBM TDB	13.44
	1	palladium))	1517_100	
20	1372	1 -	USPAT;	2002/12/13
	13/2		EPO; JPO;	13:56
		(438/479)).CCLS.	IBM TDB	13.30
	45	///429/400\ om /429/4E6\ om /429/4E0\ om	USPAT;	2002/12/13
21	45		EPO; JPO;	13:56
		(438/479)).CCLS.) and (porous and (HF or		13.36
		Hydrofluoric) and etch\$5 and (Pt or	IBM_TDB	
		platinum or Au or gold or Pd or		
	<u> </u>	palladium))		1

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